

Title (en)  
Method to deposit a material on to a workpiece

Title (de)  
Verfahren zum Aufbringen von Material auf ein Bauteil

Title (fr)  
Procédé de revêtement d'un matériau à une pièce

Publication  
**EP 1867749 A1 20071219 (DE)**

Application  
**EP 06012071 A 20060612**

Priority  
EP 06012071 A 20060612

Abstract (en)  
The applying material on a turbine blade/ring segment (1) having a substrate (4) from a first material, comprises arranging an interwoven structure comprising a second material on a substrate and coating the substrate and the interwoven structure with a coating material having third material by means of a spraying process. The first, second and third materials are same types of materials. The spraying process comprises a thermal spraying process having high-speed flame spraying. The applying material on a turbine blade/ring segment (1) having a substrate (4) from a first material, comprises arranging an interwoven structure comprising a second material on a substrate and coating the substrate and the interwoven structure with a coating material having third material by means of a spraying process. The first, second and third materials are same types of materials. The spraying process comprises a thermal spraying process having high-speed flame spraying. A thermal treatment is carried out after the coating of the substrate and the interwoven structure and comprises a solution annealing. The interwoven structure is arranged in a recess (7) of the substrate before the coating takes place.

Abstract (de)  
Die vorliegende Erfindung betrifft ein Verfahren zum Aufbringen von Material auf ein Bauteil (1), das ein Substrat (4) aus einem ersten Material umfasst. Auf dem Substrat (4) wird ein Geflecht (13) angeordnet, das ein zweites Material umfasst. Das Substrat (4) und das darauf angeordnete Geflecht (13) werden mittels eines Spritzverfahrens mit einem Beschichtungsmaterial (16) beschichtet, das ein drittes Material umfasst. Das erste, zweite und dritte Material sind artgleiche Materialien.

IPC 8 full level  
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CPC (source: EP US)  
**B23P 6/007** (2013.01 - EP); **C23C 4/01** (2016.01 - EP); **C23C 4/02** (2013.01 - EP); **C23C 4/18** (2013.01 - EP); **C23C 24/04** (2013.01 - EP); **F01D 5/005** (2013.01 - EP US); **F05D 2230/311** (2013.01 - EP); **F05D 2230/80** (2013.01 - EP); **Y02T 50/60** (2013.01 - US)

Citation (search report)

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Designated contracting state (EPC)  
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**EP 06012071 A 20060612**; EP 2007053640 W 20070413